

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS}	-30	٧		
R _{DS(on)} V _{GS} = 10 V	8	mΩ		
$R_{DS(on)}$ $V_{GS} = 4.5 \text{ V}$	11	mΩ		
I _D	-70	Α		
Configuration	Single			

FEATURES

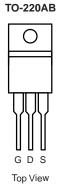
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

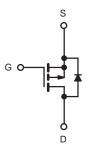
Pb-free

RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V_{GS}	± 20	v
	T _C = 25 °C		- 70	
Continuous Prain Current (T. – 150 °C)	T _C = 70 °C		- 55	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	- 55	
	T _A = 70 °C		-45	Λ.
Pulsed Drain Current	I _{DM}	- 200	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		- 50	
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	- 50	
Avalanche Current	1 04	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
Maximum Power Dissipation	T _C = 25 °C		50	
	T _C = 70 °C		32	w
	T _A = 25 °C	P _D	7 ^{a, b}	VV
	T _A = 70 °C		5 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{th,IF}	20	25]	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				l l		ı
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	In = - 250 µA		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μΑ		5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
Zana Oata Vallana Busin Oamani		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 1	μA
Zero Gate Voltage Drain Current	IDSS				- 5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
	, ,	V _{GS} = - 10 V, I _D = - 10 A	8			mΩ
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	V _{GS} = - 4.5 V, I _D = - 8 A		11		- 1115.2
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S
Dynamic ^b						ı
Input Capacitance	C _{iss}			3950		pF
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		455		
Reverse Transfer Capacitance	C _{rss}			390		
Total Gate Charge		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		57	86	
	Q _g V _{DS} = 13 v, v _{GS} = 10 v, I _D = 10 A		29.5	45	_	
Gate-Source Charge	Q _{qs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		nC
Gate-Drain Charge	Q_{gd}			22		
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24	
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_{q} = 1 \Omega$		40	70	
Fall Time	t _f	Ű		9	18	
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		92	160	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		34	60	
Fall Time	t _f	Ů		19	35	
Drain-Source Body Diode Characteris						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	_
Pulse Diode Forward Current	I _{SM}	-			- 60	Α
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	3 33		27	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1 40 A 11/1/ 400 A/ T 55 50		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		
Reverse Recovery Rise Time	t _b			15		ns

Notes:

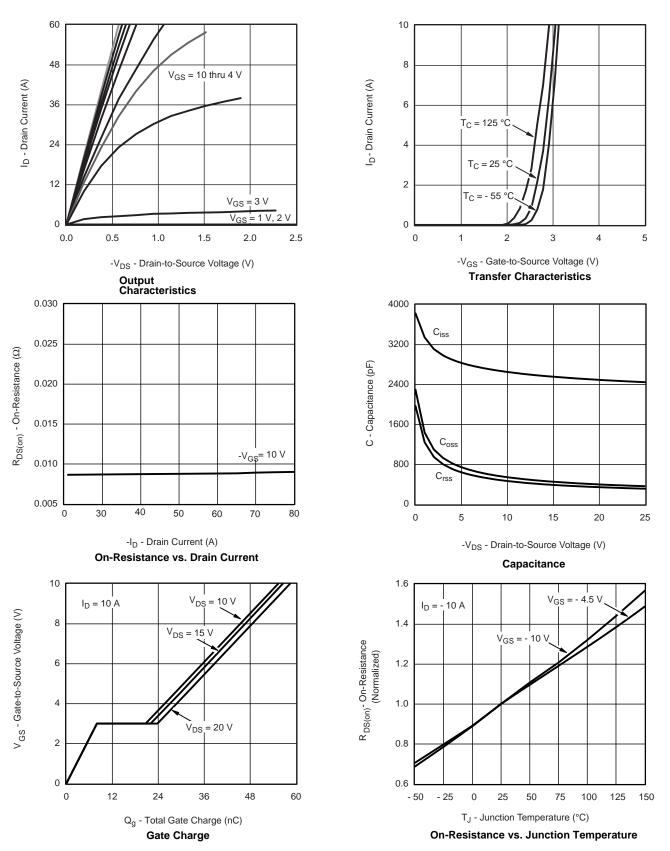
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

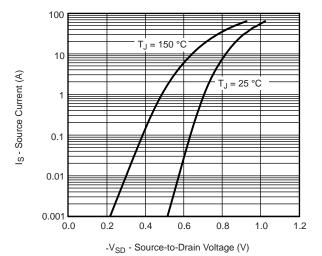


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

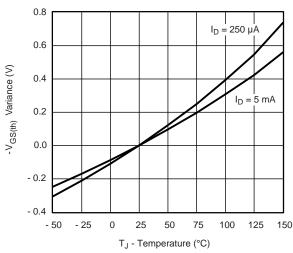




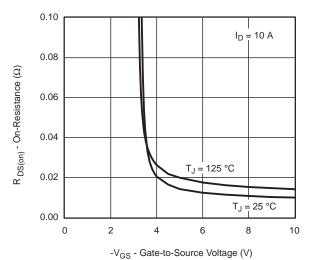
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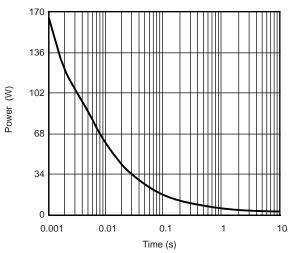
Source-Drain Diode Forward Voltage



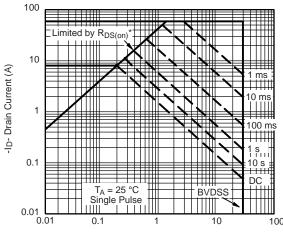
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



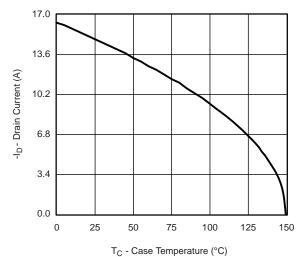
-V_{DS} - Drain-to-Source Voltage (V)

Safe Operating Area

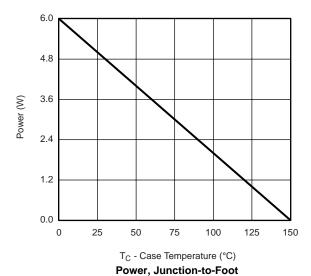
^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

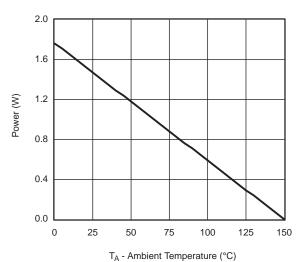


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



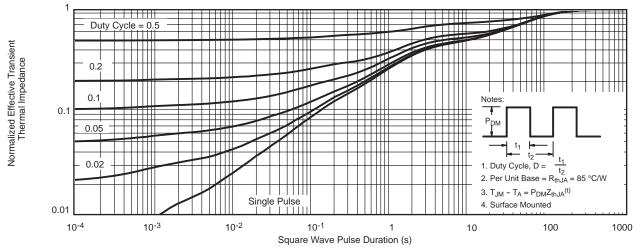


Power Derating, Junction-to-Ambient

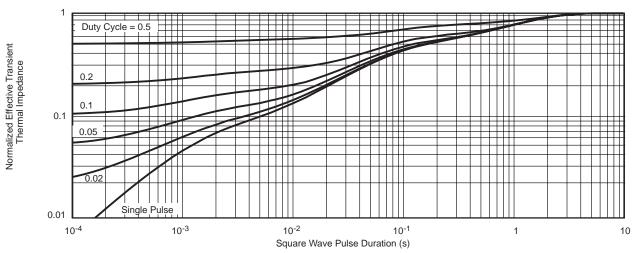
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



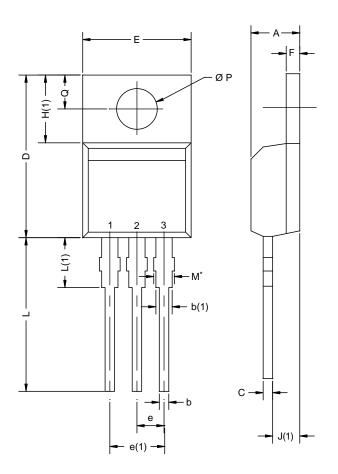
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-220AB



	MILLIMETERS			HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.25	4.65	0.167	0.183		
b	0.69	1.01	0.027	0.040		
b(1)	1.20	1.73	0.047	0.068		
С	0.36	0.61	0.014	0.024		
D	14.85	15.49	0.585	0.610		
Е	10.04	10.51	0.395	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.09	6.48	0.240	0.255		
J(1)	2.41	2.92	0.095	0.115		
L	13.35	14.02	0.526	0.552		
L(1)	3.32	3.82	0.131	0.150		
ØР	3.54	3.94	0.139	0.155		
Q	2.60	3.00	0.102	0.118		
ECN: X12-0208-Rev. N, 08-Oct-12						

DWG: 5471

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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